

Substitute Form PTO-1449 (Modified)		U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-593001	Application No. 10/060,864
<b>Information Disclosure Statement by Applicant</b> (Use several sheets if necessary)  (37 CFR §1.98(b))		DEC 09 2002 U.S. PATENT & TRADEMARK OFFICE	Applicant Steven L. Carson	
			Filing Date January 29, 2002	Group Art Unit 3636

U.S. Patent Documents							
Examiner Initial	Desig. ID	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date If Appropriate
JW	AA	US 6,071,059	06/06/00	Mages et al.			
	AB						
	AC						

Foreign Patent Documents or Published Foreign Patent Applications							
Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation
							Yes No
	AD						
	AE						

Other Documents (include Author, Title, Date, and Place of Publication)		
Examiner Initial	Desig. ID	Document
JW	AF	Jenkins et al., "in the 300 mm Environment" Semiconductor International Test Automation, Agilent Technologies, Palo Alto, CA, June 2001.
	AG	Gallagher et al., "Addressing the 300-mm challenge with new wafer-carrier architecture" Micro Magazine.com, <a href="http://www.micromagazine.com">http://www.micromagazine.com</a> , p.81, July 1999.
	AH	Chappell "Brooks promises FOUP IP for all" Semiconductor International, <a href="http://www.semiconductor.net">www.semiconductor.net</a> , San Francisco, CA, July 13, 2000.
	AI	News Release – Entegris Debuts Industry's First 300 MM Reduced-Pitch Front-Opening Shipping System FabFit™ 300 is 40 percent smaller than standard-pitch systems, <a href="http://www.mcpr.com">http://www.mcpr.com</a>
	AJ	Ottesen "Front Opening Unified Pod (FOUP) Fire Protection: A General Overview" International Sematech Technology Transfer, 2706 Montopolis Drive, Austin, TX 78741, 1999.
	AK	"Major North American IC Manufacture orders Entegris Cleaning System", <a href="http://www.empak.com">http://www.empak.com</a> , October 11, 2000.
	AL	"High-Tech public Relations: Industry Leaders", <a href="http://www.mcpr.com">www.mcpr.com</a> , October 11, 2000.
	AM	"Specific Solutions for handling of Masks and Wafers within Semiconductor Manufacturing" Dresden Transfer Brief, <a href="http://www.tu-drwsden.de/vd51/trabrief/022000/s18.htm">http://www.tu-drwsden.de/vd51/trabrief/022000/s18.htm</a> , February 2000.
	AN	"FIXLOAD™ 300mm Standard Load Port for FOUPs (Front Opening Unified Pod) BOLTS Compatible Interface, <a href="http://www.fastechn.com/products/FBU/fixedload">http://www.fastechn.com/products/FBU/fixedload</a> ", October 11, 2000.
	AO	"Atmospheric Factory Interfaces FouP LPM Load Port Module/Door Opener for 300mm FOUPs Automated or Manual Loading, <a href="http://www.brooks.com/products/ABU/factory_interfaces/flpm1.htm">http://www.brooks.com/products/ABU/factory_interfaces/flpm1.htm</a> , October 11, 2000..
	AP	"Brooks Automation Receives Additional Patent on Its FOUP-Opener Technology, <a href="http://www.fastechn.org/industry.news/0006/160.1.shtml">http://www.fastechn.org/industry.news/0006/160.1.shtml</a> , October 11, 2000.
JW	AQ	"300mm Pod Door Opener Opens the FOUP, indexes it, and uses non-reflective technology to scan wafers!" <a href="http://www.kensingtonlabs.com/products/300door/">http://www.kensingtonlabs.com/products/300door/</a> , October 11, 2000.

Examiner Signature <i>John B. Wall</i>	Date Considered <i>6/12/03</i>
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	